

ABSTRACT OF THE DISCLOSURE

An electronic device includes a semiconductor substrate in which an integrated circuit is formed; an insulating layer which is formed on the semiconductor substrate and includes an elastically deformable section; an electrode which is electrically connected with inside of the semiconductor substrate and is formed on the elastically deformable section; and a substrate on which an interconnect pattern is formed, the interconnect pattern facing the electrode and being electrically connected with the electrode. The elastically deformable section is elastically deformed in a manner to be depressed under the electrode, and presses the electrode against the interconnect pattern due to elasticity.